优尚

YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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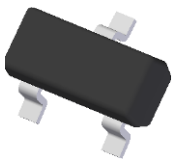
Features

- BV_{CEO} > -60V
- Darlington Transistor h_{FE} > 10k @ 100mA for high gain
- I_C = -500mA High Continuous Collector Current
- Complementary Darlington PNP Type: NK-BCV47

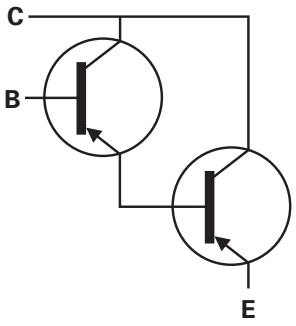
Mechanical Data

- Case: SOT23
- Case Material: molded plastic, “Green” molding compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 e3
- Weight 0.008 grams (approximate)

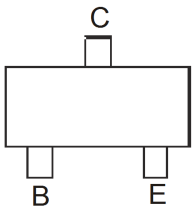
SOT23



Top View



Device Symbol



Top View
Pin-Out

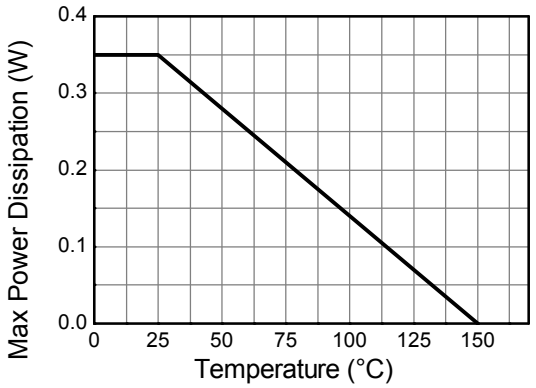
Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-80	V
Collector-Emitter Voltage	V_{CEO}	-60	V
Emitter-Base Voltage	V_{EBO}	-10	V
Continuous Collector Current	I_C	-500	mA
Peak Pulse Current	I_{CM}	-800	mA
Base Current	I_B	-100	mA

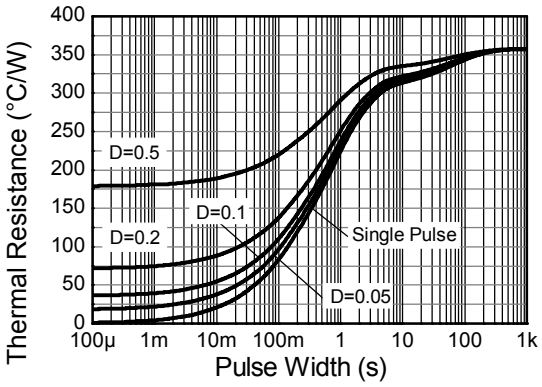
Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 6)	P_D	310	mW
	(Note 7)		350	
Thermal Resistance, Junction to Ambient	(Note 6)	$R_{\theta JA}$	403	°C/W
	(Note 7)		357	
Thermal Resistance, Junction to Leads	(Note 8)	$R_{\theta JL}$	350	°C/W
Operating and Storage Temperature Range		T_J,T_{STG}	-55 to +150	°C

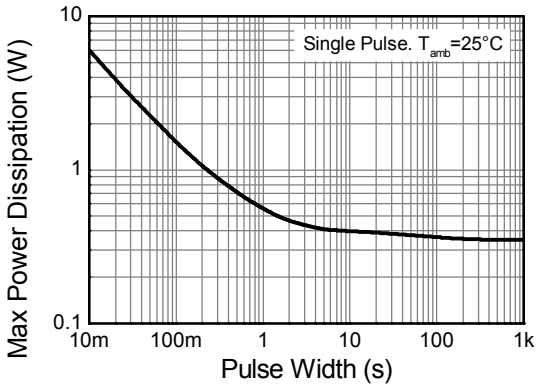
Notes:
6. For the device mounted on minimum recommended pad layout FR4 PCB with high coverage of single sided 1oz copper in still air condition; the device is measured when operating in a steady-state condition.
7. Same as note (6), except the device is mounted on 15mm x 15mm FR4 PCB.
8. Thermal resistance from junction to solder-point (at the end of the leads).



Derating Curve



Transient Thermal Impedance



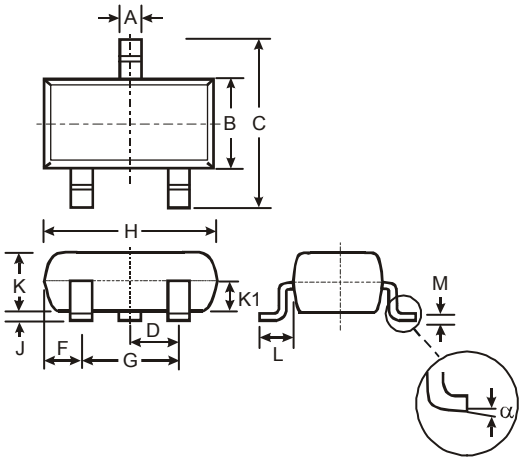
Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_{CBO}	-80	-	-	V	I_C = -100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV_{CEO}	-60	-	-	V	I_C = -10mA
Emitter-Base Breakdown Voltage	BV_{EBO}	-10	-	-	V	I_E = -10μA
Collector Cutoff Current	I_{CBO}	- -	<1 -	-100 -10	nA μA	V_{CB} = -60V V_{CB} = -60V, T_A = +150°C
Emitter Cutoff Current	I_{EBO}	-	<1	-100	nA	V_{EB} = -4V
ON CHARACTERISTICS (Note 9)						
Static Forward Current Transfer Ratio	h_{FE}	2,000 4,000 10,000 2,000	- - - -	- - - -	-	I_C = -100μA, V_{CE} = -1V I_C = -10mA, V_{CE} = -5V I_C = -100mA, V_{CE} = -5V I_C = -500mA, V_{CE} = -5V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	-	-	-1.0	V	I_C = - 100mA, I_B = -0.1mA
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	-	-	-1.5	V	I_C = -100mA, I_B = -0.1mA
SMALL SIGNAL CHARACTERISTICS						
Transition Frequency	f_T	-	200	-	MHz	V_{CE} = -5V, I_C = -50mA, f = 20MHz
Output Capacitance	C_{obo}	-	4.5	-	pF	V_{CB} = -10V, f = 1MHz

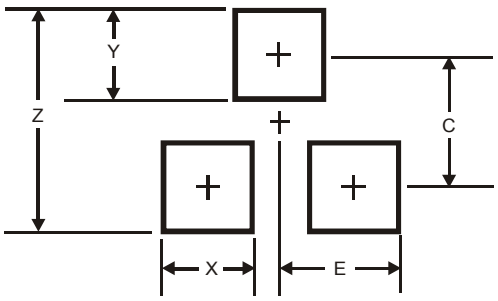
Notes: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Package Outline Dimensions



SOT23			
Dim	**Min**	**Max**	**Typ**
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35